

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

PATENT NO. : 7,094,676 B1  
APPLICATION NO. : 10/719823  
DATED : August 22, 2006  
INVENTOR(S) : Chuen-Rong Leu et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On Title Page, Item (54) should read,  
METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH AN  
EMBEDDED METAL PILLAR.

Column 53

Lines 31-36, "providing a metal base . . . of the metal base;" is a subparagraph.  
Line 33, delete ";;" after "the".

Column 55

Lines 46-51, "providing a metal base . . . of the metal base;" is a subparagraph.  
Line 48, delete ";;" after "the".

Column 57

Lines 56-61, "providing a metal base . . . of the metal base;" is a subparagraph.  
Line 58, delete ";;" after "the".

Column 60

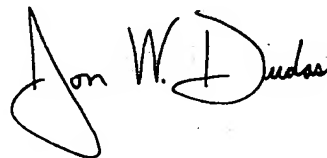
Lines 15-20, "providing a metal base . . . of the metal base;" is a subparagraph.  
Line 17, delete ";;" after "the".

Column 71

Line 16, change "291" to -- 293 --.

Signed and Sealed this

Twenty-fourth Day of October, 2006

A handwritten signature in black ink, appearing to read "Jon W. Dudas". The signature is stylized with a large, looping initial "J" and a distinct "D".

JON W. DUDAS  
*Director of the United States Patent and Trademark Office*